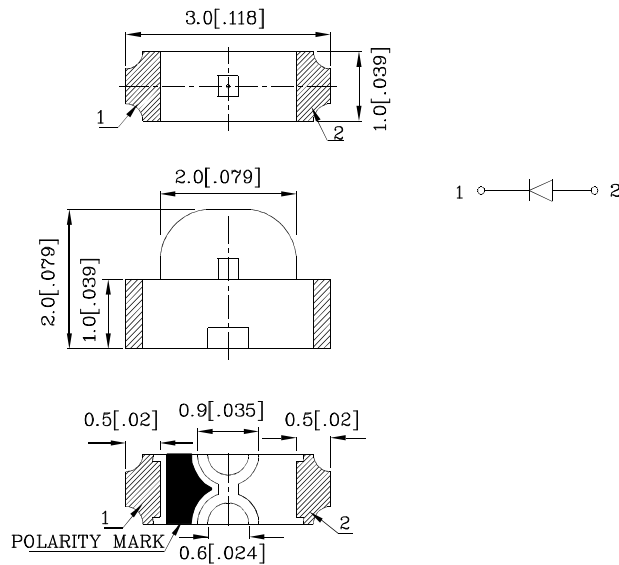


Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Tinned pads for improved solderability
- Package : 2000pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant



Package Schematics

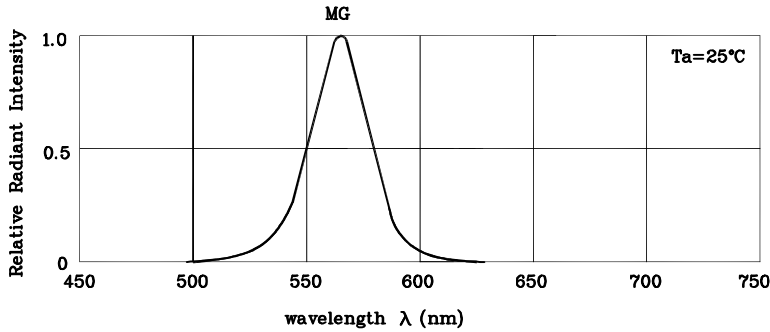


- Notes:
1. All dimensions are in millimeters (inches).
 2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.
 3. Specifications are subject to change without notice.

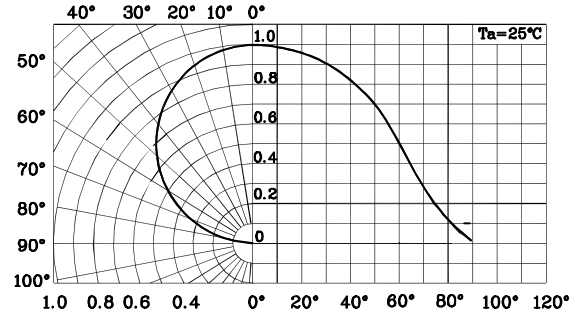
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	mA
Power Dissipation	P_D	62.5	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	

Operating Characteristics ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	565	nm
Wavelength of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZMG56WT-5	Green	GaP	Water Clear	8	14	565	120°

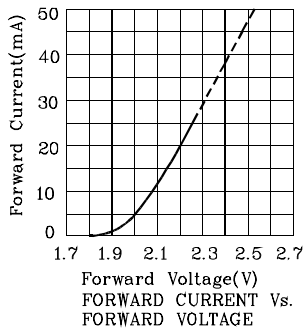


RELATIVE INTENSITY Vs. WAVELENGTH

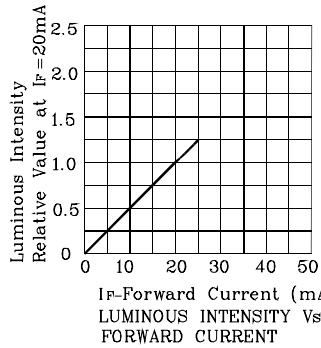


SPATIAL DISTRIBUTION

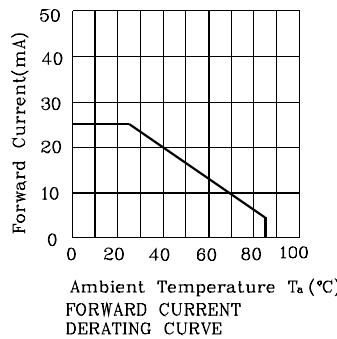
❖ MG



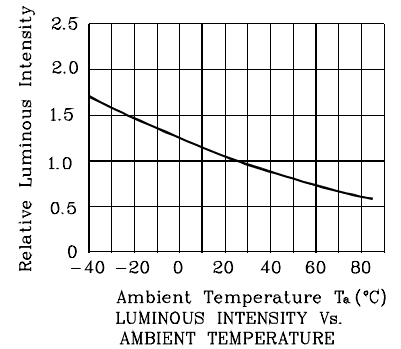
FORWARD CURRENT(V)
FORWARD CURRENT Vs.
FORWARD VOLTAGE



If=Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



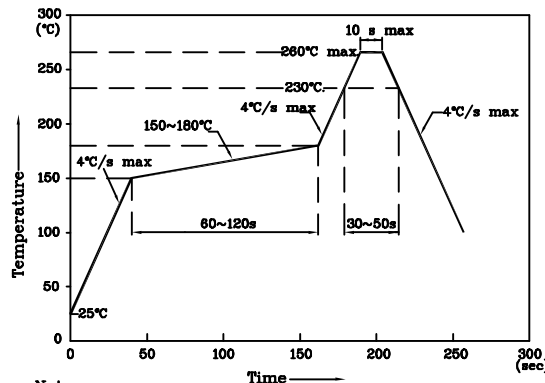
Ambient Temperature T_a (°C)
FORWARD CURRENT
DERATING CURVE



Ambient Temperature T_a (°C)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

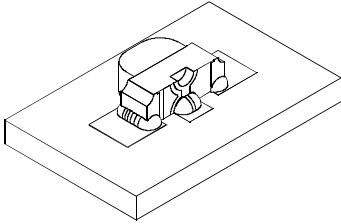


Notes:

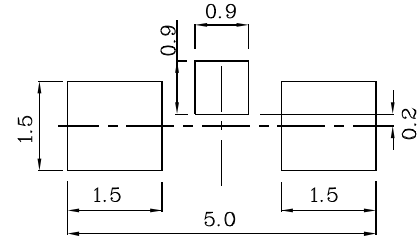
1. Maximum soldering temperature should not exceed 280°C
2. Recommended reflow temperature: 145°C-260°C
3. Do not put stress to the epoxy resin during high temperatures conditions



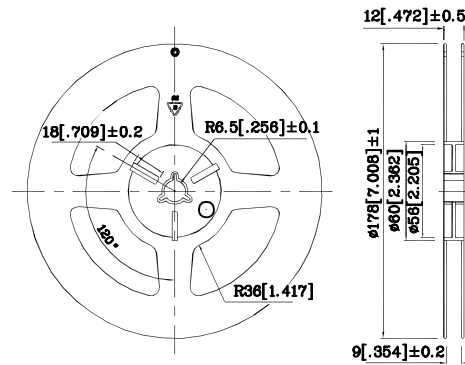
❖ The device has a single mounting surface.
The device must be mounted according to the specifications.



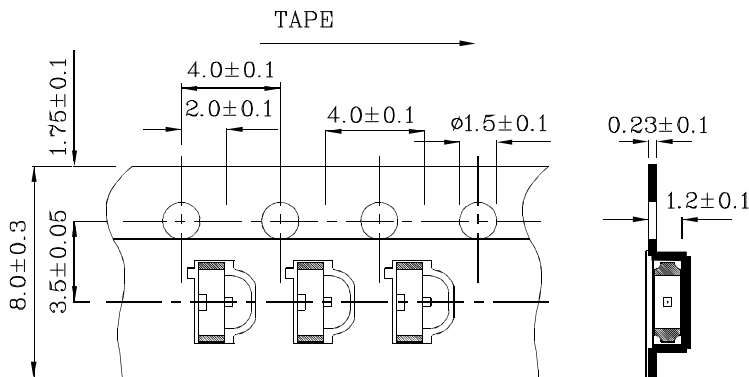
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units : mm)



Remarks:

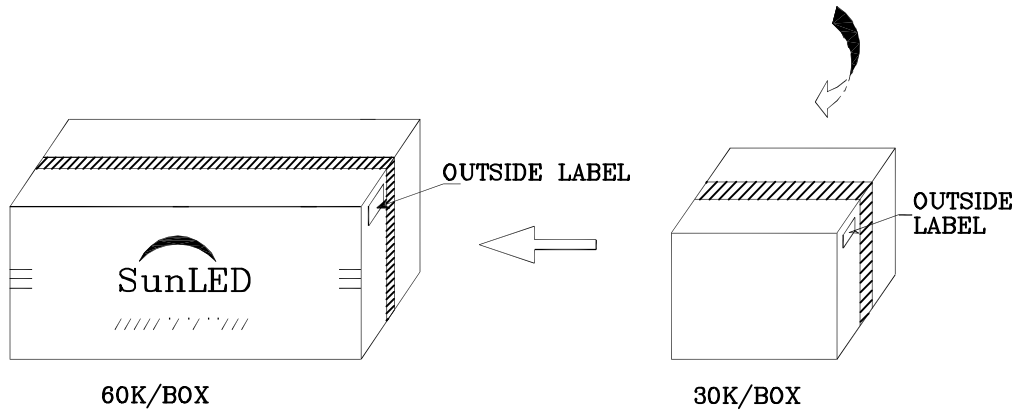
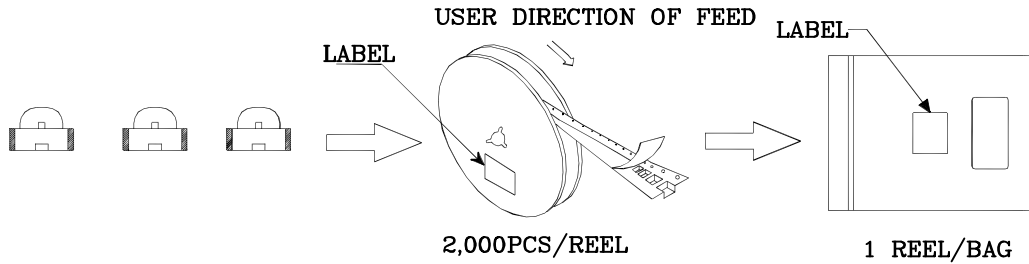

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

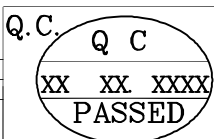

1. Wavelength: $\pm 1\text{nm}$
2. Luminous intensity / luminous flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS

	
P/N0 : XZxx56xx	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	